	© Co	terial Compo pyright 2005. IPC, Bannoc nternational and Pan-Ameri	kburn, Illinois	. All rights reserv	tion with lowe	er level	parts, the	declarati	on encor		er level mat	erials for	which th	item is an assembly e manufacturer has eclaration.		
	-	Web Site for Informat ://www.ipc.org/IPC-1		-1752 Standa	ırd					claration Class * ss 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat						
Supplier Information																
Company Name *		Company Unique ID		Unique ID Au	uthority	Resp	onse Dat	e *		Response Doci	ument ID					
Cypress Semiconductor	CYPRESS			2009	09-04											
Contact Name * Richard Oshiro	-			I - Contac cypress.	-		Duplicate Contact -> Authorized Representative									
Authorized Representati Glorioso Lutrinia	9	· ·			Email - Representative * Ige@cypress.com			Supplier Comments or URL for Additional Information http://app.cypress.com/portal/server.pt?space=Community								
Requester Item Number	r	Mfr Item Number		Mfr Item Name			Effective Date Version Manu		Manufa	cturing Site	Weight *	UOI	М	Unit Type		
		TQFP 100 14 x 20 m	ım	TQFP 100 14	x 20 mm	2009-	09-04	ASE			942	mg	J	Each		
Alternate Recommenda	ation							Alternat	e Item Co	mments Packa	age QTP No. 034101					
Manufacturing Proces	ss In	formation						•								
Terminal Plating / Grid Array I	Mater	ial	Base Alloy J-STD-020 MSL Ra			ting Peak Process Body Tempe			ature Max Time	at Peak Tem	perature	Number c	f Reflow Cycles			
Tin (Sn) Comments	/	3			260			C 40 seconds 3								
Compliant to RoHS and	Halo	gen Requirements														

Save the fields in this form to a file	Export Data	Import fields from a file into this form	Import Data	Clear all of the fields on this form	Reset Form	Lock the fields on this form to prevent chan	Look Cumption Fields						
<b>RoHS Material</b>	RoHS Material Composition Declaration Declaration Type * Detailed												
		limit of 0.1% by mass (100 thers (PBDE) and quantity	, .				ominated Biphenyls (PBB),						
chromium, polybrominate excess of an applicable of gathered the information Company will rely on this completing this form, and certifications regarding the conditions of that agreen	ed biphenyls and/or polybrominated quantity limit, please indicate below it provides in this form using approp certification in determining the com I that Supplier may not have independent rein contributions to the part, and the nent, including any warranty rights a	which, if any, RoHS exemption you b priate methods to ensure its accuracy apliance of its products with European andently verified such information. Ho pose certifications are at least as comp	icted substance") in excess believe may apply. If the p y and that such information n Union member state laws bowever, in situations where prehensive as the certification that agreement, will be the s	of the applicable quantity limit bart is an assembly with lower I is true and correct to the best of that implement the RoHS Dire Supplier has not independentl on in this paragraph. If the Co ole and exclusive source of the	identified above. If a homogene- evel components, the declaration of its knowledge and belief, as of ctive. Company acknowledges to y verified information provided by mpany and the Supplier enter into a Supplier's liability and the Comp	eous material within the part cont n shall encompass all such comp f the date that Supplier complete that Supplier may have relied on y others, Supplier agrees that, at to a written agreement with response upany's remedies for issues that a	tains a RoHS restricted substance in ponents. Supplier certifies that it s this form. Supplier acknowledges that						
RoHS Declaration	n * 1 - Item(s) does not contain	RoHS restricted substances per th	he definition above			Supplier Acceptance *	Accepted						
	declared item does not cont Il applicable exemptions.	ain RoHS restricted substanc	es per the definition a	bove except for defined	RoHS exemptions, then s	select the corresponding re	esponse in the RoHS Declaration						
Declaration Si	gnature												
		C 1 1 11 C (1 1 )			· • • • • •	<b>T</b> 1: 10 11 1 4	D' i ll i						

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## Homogeneous Material Composition Declaration for Electronic Products

**Subltem Instructions:** The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

		Item/SubItem		Woldht		Unit of			Level	Substance Category			Substance	CAS	Exempt	Weight	Unit of	Tolerance		PPM
		Name		Material	Weight	Measure			Level	oubstance outegory			oubstance		Lyempt	weight	Measure	-	+	
+I	-I	Leadframe	+M -M	Base Material	242.01	mg	+C	-C	Supplier	Copper	+S	-S	Copper	7440-50-8		227.96	mg			242,00
			_				+C	-C	Supplier	Ni	+S	-S	Ni			7.07	mg			7,500
							+C	-C	Supplier	Si	+S	-S	Si	7440-21-3		1.51	mg			1,600
							+C	-C	Supplier	Mg	+S	-S	Mg	7439-95-4		0.38	mg			400
							+C	-C	Supplier	Ag	+S	-S	Ag	7440-22-4		5.09	mg			5,400
+1	-I	Leadfinish	+M -M	External Plating	16.49	mg	+C	-C	Supplier	Sn	+S	-S	Sn	7440-31-5		16.49	mg			17,500
+I	-	Die Attach	+M -M	Adhesive	3.38	mg	+C	-C	Supplier	Ag	+S	-S	Ag	7440-22-4		2.45	mg			2,600
							+C	-C	Supplier	Epoxy Resin	+S	-S	Epoxy Resin	Proprietary		0.66	mg			700
							+C	-C	Supplier	Copper	+S	-S	Copper	7440-50-8		0.09	mg			100
							+C	-C	Supplier	Gamma- Butyrolacto	+S	-S	Gamma- Butyrolactone	96-48-0		0.09	mg			100
							+C	-C	Supplier	Aromatic Hydrocarbo	+S	-S	Aromatic Hydrocarbons	Proprietary		0.09	mg			100
+1	-I	Die	+M -M	Silicon Die	20.72	mg	+C	-C	Supplier	Silicon	+S	-S	Silicon	7440-21-3		20.72	mg			22,000
+I	-	Goldwire	+M -M	Interconnect	4.52	mg	+C	-C	Supplier	Gold	+S	-S	Gold	7440-57-5		4.52	mg			4,800
+I	-	Mold Compound	+M -M	Encapsulation	654.88	mg	+C	-C	Supplier	Epoxy Resin	+S	-S	Epoxy Resin	85954-11-6		32.78	mg			34,800
			_				+C	-C	Supplier	Phenol resin	+S	-S	Phenol resin	26834-02-6		26.19	mg			27,800
							+C	-C	Supplier	SiO2	+S	-S	SiO2	60676-86-0		579.52	mg			615,20
							+C	-C	Supplier	Aromatic Phosphate	+S	-S	Aromatic Phosphate	139189-30-3		9.8	mg			10,400
							+C	-C	Supplier	Others	+S	-S	Others	Proprietary		6.59	mg			7,000